

Data sheet acquired from Harris Semiconductor SCHS204J

February 1998 - Revised December 2003

High-Speed CMOS Logic Phase-Locked Loop with VCO

Features

- Operating Frequency Range
 - Up to 18MHz (Typ) at $V_{CC} = 5V$
 - Minimum Center Frequency of 12MHz at V_{CC} = 4.5V
- · Choice of Three Phase Comparators
 - EXCLUSIVE-OR
 - Edge-Triggered JK Flip-Flop
 - Edge-Triggered RS Flip-Flop
- Excellent VCO Frequency Linearity
- VCO-Inhibit Control for ON/OFF Keying and for Low Standby Power Consumption
- Minimal Frequency Drift
- Operating Power Supply Voltage Range

 - Digital Section2V to 6V
- Fanout (Over Temperature Range)
 - Standard Outputs......10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility,
 V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)
 - CMOS Input Compatibility, $I_I \le 1\mu A$ at VOL, VOH

Applications

- FM Modulation and Demodulation
- · Frequency Synthesis and Multiplication
- Frequency Discrimination
- Tone Decoding
- Data Synchronization and Conditioning
- Voltage-to-Frequency Conversion
- Motor-Speed Control

Description

The 'HC4046A and 'HCT4046A are high-speed silicon-gate CMOS devices that are pin compatible with the CD4046B of the "4000B" series. They are specified in compliance with JEDEC standard number 7.

The 'HC4046A and 'HCT4046A are phase-locked-loop circuits that contain a linear voltage-controlled oscillator (VCO) and three different phase comparators (PC1, PC2 and PC3). A signal input and a comparator input are common to each comparator.

The signal input can be directly coupled to large voltage signals, or indirectly coupled (with a series capacitor) to small voltage signals. A self-bias input circuit keeps small voltage signals within the linear region of the input amplifiers. With a passive low-pass filter, the 4046A forms a second-order loop PLL. The excellent VCO linearity is achieved by the use of linear op-amp techniques.

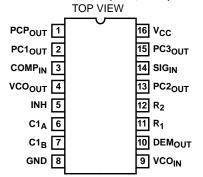
Ordering Information

PART NUMBER	TEMP. RANGE (^O C)	PACKAGE
CD54HC4046AF3A	-55 to 125	16 Ld CERDIP
CD54HCT4046AF3A	-55 to 125	16 Ld CERDIP
CD74HC4046AE	-55 to 125	16 Ld PDIP
CD74HC4046AM	-55 to 125	16 Ld SOIC
CD74HC4046AMT	-55 to 125	16 Ld SOIC
CD74HC4046AM96	-55 to 125	16 Ld SOIC
CD74HC4046ANSR	-55 to 125	16 Ld SOP
CD74HC4046APWR	-55 to 125	16 Ld TSSOP
CD74HC4046APWT	-55 to 125	16 Ld TSSOP
CD74HCT4046AE	-55 to 125	16 Ld PDIP
CD74HCT4046AM	-55 to 125	16 Ld SOIC
CD74HCT4046AMT	-55 to 125	16 Ld SOIC
CD74HCT4046AM96	-55 to 125	16 Ld SOIC

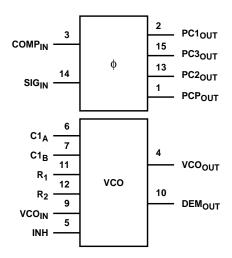
NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

Pinout

CD54HC4046A, CD54HCT4046A (CERDIP) CD74HC4046A (PDIP, SOIC, SOP, TSSOP) CD74HCT4046A (PDIP, SOIC)



Functional Diagram



Pin Descriptions

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1	PCP _{OUT}	Phase Comparator Pulse Output
2	PC1 _{OUT}	Phase Comparator 1 Output
3	COMPIN	Comparator Input
4	VCO _{OUT}	VCO Output
5	INH	Inhibit Input
6	C1 _A	Capacitor C1 Connection A
7	C1 _B	Capacitor C1 Connection B
8	GND	Ground (0V)
9	VCO _{IN}	VCO Input
10	DEM _{OUT}	Demodulator Output
11	R ₁	Resistor R1 Connection
12	R ₂	Resistor R2 Connection
13	PC2 _{OUT}	Phase Comparator 2 Output
14	SIG _{IN}	Signal Input
15	PC3 _{OUT}	Phase Comparator 3 Output
16	V _{CC}	Positive Supply Voltage

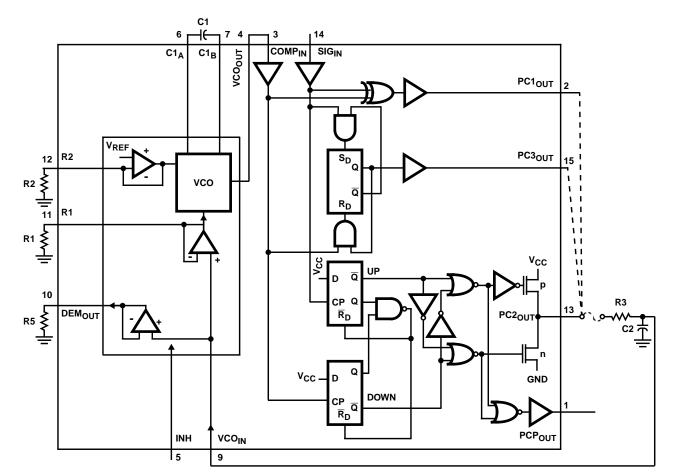


FIGURE 1. LOGIC DIAGRAM

General Description

VCO

The VCO requires one external capacitor C1 (between C1_A and C1_B) and one external resistor R1 (between R₁ and GND) or two external resistors R1 and R2 (between R₁ and GND, and R₂ and GND). Resistor R1 and capacitor C1 determine the frequency range of the VCO. Resistor R2 enables the VCO to have a frequency offset if required. See logic diagram, Figure 1.

The high input impedance of the VCO simplifies the design of low-pass filters by giving the designer a wide choice of resistor/capacitor ranges. In order not to load the low-pass filter, a demodulator output of the VCO input voltage is provided at pin 10 (DEMOUT). In contrast to conventional techniques where the DEMOUT voltage is one threshold voltage lower than the VCO input voltage, here the DEMOUT voltage equals that of the VCO input. If DEMOUT is used, a load resistor (RS) should be connected from DEMOUT to GND; if unused, DEMOUT should be left open. The VCO output (VCO_{OUT}) can be connected directly to the comparator input (COMPIN), or connected via a frequencydivider. The VCO output signal has a specified duty factor of 50%. A LOW level at the inhibit input (INH) enables the VCO and demodulator, while a HIGH level turns both off to minimize standby power consumption.

Phase Comparators

The signal input (SIG_{IN}) can be directly coupled to the self-biasing amplifier at pin 14, provided that the signal swing is between the standard HC family input logic levels. Capacitive coupling is required for signals with smaller swings.

Phase Comparator 1 (PC1)

This is an Exclusive-OR network. The signal and comparator input frequencies (f_i) must have a 50% duty factor to obtain the maximum locking range. The transfer characteristic of PC1, assuming ripple $(f_r = 2f_j)$ is suppressed, is:

 $V_{DEMOUT} = (V_{CC}/\pi)$ ($\phi SIG_{IN} - \phi COMP_{IN}$) where V_{DEMOUT} is the demodulator output at pin 10; $V_{DEMOUT} = V_{PC1OUT}$ (via low-pass filter).

The average output voltage from PC1, fed to the VCO input via the low-pass filter and seen at the demodulator output at pin 10 (VDEMOUT), is the resultant of the phase differences of signals (SIGIN) and the comparator input (COMPIN) as shown in Figure 2. The average of VDEM is equal to 1/2 VCC when there is no signal or noise at SIGIN, and with this input the VCO oscillates at the center frequency (fo). Typical waveforms for the PC1 loop locked at fo are shown in Figure 3.

The frequency capture range $(2f_C)$ is defined as the frequency range of input signals on which the PLL will lock if it was initially out-of-lock. The frequency lock range $(2f_L)$ is defined as the frequency range of input signals on which the loop will stay locked if it was initially in lock. The capture range is smaller or equal to the lock range.

With PC1, the capture range depends on the low-pass filter characteristics and can be made as large as the lock range. This configuration retains lock behavior even with very noisy input signals. Typical of this type of phase comparator is that it can lock to input frequencies close to the harmonics of the VCO center frequency.

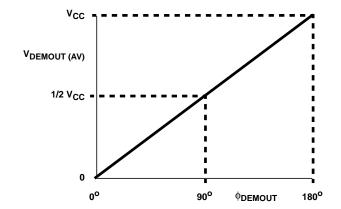


FIGURE 2. PHASE COMPARATOR 1: AVERAGE OUTPUT VOLTAGE vs INPUT PHASE DIFFERENCE: $V_{DEMOUT} = V_{PC1OUT} = (V_{CC}/\pi) (\phi SIG_{IN} - \phi COMP_{IN}); \phi_{DEMOUT} = (\phi SIG_{IN} - \phi COMP_{IN})$

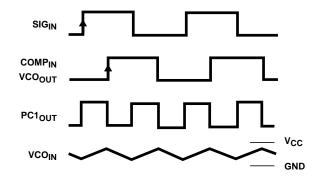


FIGURE 3. TYPICAL WAVEFORMS FOR PLL USING PHASE COMPARATOR 1, LOOP LOCKED AT f_0

Phase Comparator 2 (PC2)

This is a positive edge-triggered phase and frequency detector. When the PLL is using this comparator, the loop is controlled by positive signal transitions and the duty factors of ${\sf SIG_{IN}}$ and ${\sf COMP_{IN}}$ are not important. PC2 comprises two D-type flip-flops, control-gating and a three-state output stage. The circuit functions as an up-down counter (Figure 1) where ${\sf SIG_{IN}}$ causes an up-count and ${\sf COMP_{IN}}$ a down-count. The transfer function of PC2, assuming ripple (fr = fi) is suppressed, is:

The average output voltage from PC2, fed to the VCO via the low-pass filter and seen at the demodulator output at pin 10 (V_{DEMOUT}), is the resultant of the phase differences of SIG_{IN} and $COMP_{IN}$ as shown in Figure 4. Typical waveforms for the PC2 loop locked at f_0 are shown in Figure 5.

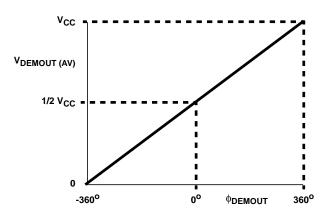


FIGURE 4. PHASE COMPARATOR 2: AVERAGE OUTPUT VOLTAGE vs INPUT PHASE DIFFERENCE: VDEMOUT = VPC2OUT

= $(V_{CC}/4\pi)$ (ϕ SIG_{IN} - ϕ COMP_{IN}); ϕ DEMOUT = $(\phi$ SIG_{IN} - ϕ COMP_{IN})

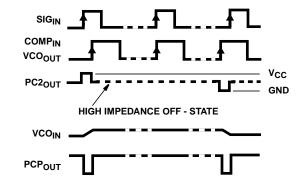


FIGURE 5. TYPICAL WAVEFORMS FOR PLL USING PHASE COMPARATOR 2, LOOP LOCKED AT $f_{\rm O}$

When the frequencies of SIG_{IN} and COMP_{IN} are equal but the phase of SIG_{IN} leads that of COMP_{IN}, the p-type output driver at PC2_{OUT} is held "ON" for a time corresponding to the phase difference (ϕ_{DEMOUT}). When the phase of SIG_{IN} lags that of COMP_{IN}, the n-type driver is held "ON".

When the frequency of SIG_{IN} is higher than that of $COMP_{IN}$, the p-type output driver is held "ON" for most of the input signal cycle time, and for the remainder of the cycle both n- and p-type drivers are "OFF" (three-state). If the SIG_{IN} frequency is lower than the $COMP_{IN}$ frequency, then it is the n-type driver that is held "ON" for most of the cycle. Subsequently, the voltage at the capacitor (C2) of the low-pass filter connected to $PC2_{OUT}$ varies until the signal and comparator inputs are equal in both phase and

frequency. At this stable point the voltage on C2 remains constant as the PC2 output is in three-state and the VCO input at pin 9 is a high impedance. Also in this condition, the signal at the phase comparator pulse output (PCP_{OUT}) is a HIGH level and so can be used for indicating a locked condition.

Thus, for PC2, no phase difference exists between SIG_{IN} and $COMP_{IN}$ over the full frequency range of the VCO. Moreover, the power dissipation due to the low-pass filter is reduced because both p- and n-type drivers are "OFF" for most of the signal input cycle. It should be noted that the PLL lock range for this type of phase comparator is equal to the capture range and is independent of the low-pass filter. With no signal present at SIG_{IN} , the VCO adjusts, via PC2, to its lowest frequency.

Phase Comparator 3 (PC3)

This is a positive edge-triggered sequential phase detector using an RS-type flip-flop. When the PLL is using this comparator, the loop is controlled by positive signal transitions and the duty factors of SIG_{IN} and $COMP_{IN}$ are not important. The transfer characteristic of PC3, assuming ripple ($f_r = f_i$) is suppressed, is:

 $V_{DEMOUT} = (V_{CC}/2p)$ (fSIG_{IN} - fCOMP_{IN}) where V_{DEMOUT} is the demodulator output at pin 10; $V_{DEMOUT} = V_{PC3OUT}$ (via low-pass filter).

The average output from PC3, fed to the VCO via the low-pass filter and seen at the demodulator at pin 10 (V_{DEMOUT}), is the resultant of the phase differences of SIGIN and COMPIN as shown in Figure 6. Typical waveforms for the PC3 loop locked at f_0 are shown in Figure 7.

The phase-to-output response characteristic of PC3 (Figure 6) differs from that of PC2 in that the phase angle between SIG_{IN} and COMP_{IN} varies between 0° and 360° and is 180° at the center frequency. Also PC3 gives a greater voltage swing than PC2 for input phase differences but as aconsequence the ripple content of the VCO input signal is higher. With no signal present at SIG_{IN}, the VCO adjusts, via PC3, to its highest frequency.

The only difference between the HC and HCT versions is the input level specification of the INH input. This input disables the VCO section. The comparator's sections are identical, so that there is no difference in the ${\rm SIG_{IN}}$ (pin 14) or ${\rm COMP_{IN}}$ (pin 3) inputs between the HC and the HCT versions.

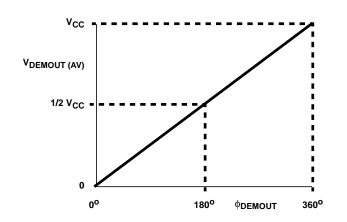


FIGURE 6. PHASE COMPARATOR 3: AVERAGE OUTPUT VOLTAGE vs INPUT PHASE DIFFERENCE:

 $\begin{aligned} & V_{DEMOUT} = V_{PC3OUT} \\ & = (V_{CC}/2\pi) \text{ } (\phi \text{SIG}_{\text{IN}} - \phi \text{COMP}_{\text{IN}}); \\ & \phi_{DEMOUT} = (\phi \text{SIG}_{\text{IN}} - \phi \text{COMP}_{\text{IN}}) \end{aligned}$

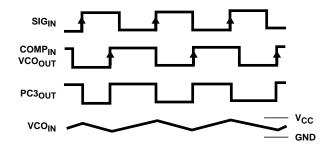


FIGURE 7. TYPICAL WAVEFORMS FOR PLL USING PHASE COMPARATOR 3, LOOP LOCKED AT $f_{\rm o}$

 2V
 1000ns (Max)

 4.5V
 500ns (Max)

 6V
 400ns (Max)

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 1):
E (PDIP) Package
M (SOIC) Package73°C/W
NS (SOP) Package
PW (TSSOP) Package
Maximum Junction Temperature
Maximum Storage Temperature Range65°C to 150°C
Maximum Lead Temperature (Soldering 10s)300°C
(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

Supply Voltage Range, V_{CC}

Input Rise and Fall Time

		TES CONDI		V _{CC}		25°C		-40°C 1	O 85°C	-55°C T	O 125°C	
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES												
VCO SECTION												
INH High Level Input	V _{IH}	-	-	3	2.1	•	-	2.1	-	2.1	-	V
Voltage				4.5	3.15	ı	-	3.15	-	3.15	-	V
				6	4.2	ı	-	4.2	-	4.2	-	V
INH Low Level Input	V _{IL}	-	-	3	-	-	0.9	-	0.9	-	0.9	V
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
VCO _{OUT} High Level	V _{OH}	V _{IH} or V _{IL}	-0.02	3	2.9	-	-	2.9	-	2.9	-	V
Output Voltage CMOS Loads			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
OWOO Loads			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
VCO _{OUT} High Level]		-	-	-	-	-	-	-	-	-	V
Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
TTE Eddus			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
VCO _{OUT} Low Level	V _{OL}	V _{IH} or V _{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
Output Voltage CMOS Loads			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
OWOO Loads			0.02	6	-	-	0.1	-	0.1	-	0.1	V
VCO _{OUT} Low Level			-	-	-	-	-	-	-	-	-	V
Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
TTE LUAUS			5.2	6	-	-	0.26	-	0.33	-	0.4	V
C1A, C1B Low Level	V _{OL}	V _{IL} or V _{IH}	4	4.5	-	-	0.40	-	0.47	-	0.54	V
Output Voltage (Test Purposes Only)			5.2	6	-	-	0.40	-	0.47	-	0.54	V

DC Electrical Specifications (Continued)

		CONDI		V _{CC}		25°C		-40°C 1	го 85°C	-55°C T	O 125°C	
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
INH VCO _{IN} Input Leakage Current	Ι _Ι	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	μΑ
R1 Range (Note 2)	-	-	-	4.5	3	-	300	-	-	-	-	kΩ
R2 Range (Note 2)	-	-	-	4.5	3	-	300	-	-	-	-	kΩ
C1 Capacitance	-	-	-	3	-	-	No	-	-	-	-	pF
Range				4.5	-	-	Limit	-	-	-	-	pF
				6	-	-	1	-	-	-	-	pF
VCO _{IN} Operating	-	Over the	range	3	1.1	-	1.9	-	-	-	-	V
Voltage Range		specified f		4.5	1.1	-	3.2	-	-	-	-	V
		10, and (Note	34 - 37	6	1.1	-	4.6	-	-	-	-	V
PHASE COMPARATO	R SECTIO	N										
SIG _{IN} , COMP _{IN}	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
DC Coupled High-Level Input				4.5	3.15	-	-	3.15	-	3.15	-	V
Voltage				6	4.2	-	-	4.2	-	4.2	-	V
SIG _{IN} , COMP _{IN}	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
DC Coupled				4.5	-	-	1.35	-	1.35	-	1.35	V
Low-Level Input Voltage				6	-	-	1.8	-	1.8	-	1.8	V
PCP _{OUT} , PCn OUT	V _{OH}	V _{IL} or V _{IH}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
High-Level Output		"- "'		4.5	4.4	-	-	4.4	-	4.4	-	V
Voltage CMOS Loads				6	5.9	-	-	5.9	-	5.9	-	V
PCP _{OUT} , PCn OUT	Voh	V _{IL} or V _{IH}	-4	4.5	3.98	-	-	3.84	-	3.7	-	V
High-Level Output Voltage TTL Loads			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
PCP _{OUT} , PCn OUT	V _{OL}	V _{IL} or V _{IH}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
Low-Level Output				4.5	-	-	0.1	-	0.1	-	0.1	V
Voltage CMOS Loads				6	-	-	0.1	-	0.1	-	0.1	V
PCP _{OUT} , PCn OUT	V _{OL}	V _{IL} or V _{IH}	4	4.5	-	-	0.26	-	0.33	-	0.4	V
Low-Level Output Voltage TTL Loads			5.2	6	-	-	0.26	-	0.33	-	0.4	V
SIG _{IN} , COMP _{IN} Input	l _l	V _{CC} or	-	2	-	-	±3	-	±4	-	±5	μΑ
Leakage Current		GND		3	-	-	±7	-	±9	-	±11	μΑ
				4.5	-	-	±18	-	±23	-	±29	μΑ
				6	-	-	±30	-	±38	-	±45	μΑ
PC2 _{OUT} Three-State Off-State Current	l _{OZ}	V _{IL} or V _{IH}	-	6	-	-	±0.5	-	±5	-	±10	μА
SIG _{IN} , COMP _{IN} Input	R _I	V _I at Se		3	-	800	-	-	-	-	-	kΩ
Resistance		Operatio $\Delta V_I = 0$		4.5	-	250	-	-	-	-	-	kΩ
		See Fig		6	-	150	-	-	-	-	-	kΩ
DEMODULATOR SEC	TION	•					•					
Resistor Range	R _S	at R _S >		3	50	-	300	-	-	-	-	kΩ
		Leakage Can Infl		4.5	50	-	300	-	-	-	-	kΩ
		V _{DEM}		6	50	-	300	-	-	-	-	kΩ

DC Electrical Specifications (Continued)

		CONDI		V _{CC}		25°C		-40°C 1	го 85°С	-55°C T	O 125°C	
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Offset Voltage VCO _{IN}	V _{OFF}	$V_I = V_{VC}$	CO IN =	3	-	±30	-	-	-	-	-	mV
to V _{DEM}		V _{CC}		4.5	-	±20	-	-	-	-	-	mV
		Values Tal R _S Ra See Fig	ange	6	-	±10	-	-	-	-	-	mV
Dynamic Output	R _D	VDEMO	DUT =	3	-	25	-	-	-	-	-	Ω
Resistance at		$\frac{V_{CC}}{2}$		4.5	-	25	-	-	-	-	-	Ω
DEM _{OUT}		2		6	-	25	-	-	-	-	-	Ω
Quiescent Device Current	Icc	Pins 3, 5 at V _{CC} F GND, I ₁ a and 14 exclu	Pin 9 at at Pins 3 to be	6	-	-	8	-	80	-	160	μА
HCT TYPES	•		<u> </u>						!		•	
VCO SECTION												
INH High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
INH Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
VCO _{OUT} High Level Output Voltage CMOS Loads	V _{ОН}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
VCO _{OUT} High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
VCO _{OUT} Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
VCO _{OUT} Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
C1A, C1B Low Level Output Voltage (Test Purposes Only)	V _{OL}	V _{IH} or V _{IL}	4	4.5	-	-	0.40	-	0.47	-	0.54	V
INH VCO _{IN} Input Leakage Current	lı	Any Vo Between V GN	V_{CC} and	5.5	-		±0.1	-	±1	-	±1	μА
R1 Range (Note 2)	-	-	-	4.5	3	-	300	-	-	-	-	kΩ
R2 Range (Note 2)	-	-	-	4.5	3	-	300	-	-	-	-	kΩ
C1 Capacitance Range	-	-	-	4.5	0	-	No Limit	-	-	-	-	pF
VCO _{IN} Operating Voltage Range	-	Over the specified f Linearity So 10, and (Note	or R1 for ee Figure 34 - 37	4.5	1.1	-	3.2	-	-	-	-	V
PHASE COMPARATO	OR SECTIO	N										
SIG _{IN} , COMP _{IN} DC Coupled High-Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V

DC Electrical Specifications (Continued)

		TE:		Vcc		25°C		-40°C 1	го 85°C	-55°C T	O 125°C	
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
SIG _{IN} , COMP _{IN} DC Coupled Low-Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
PCP _{OUT} , PCn OUT High-Level Output Voltage CMOS Loads	V _{OH}	V _{IL} or V _{IH}	-	4.5	4.4	-	-	4.4	-	4.4	-	V
PCP _{OUT} , PCn OUT High-Level Output Voltage TTL Loads	V _{OH}	V _{IL} or V _{IH}	-	4.5	3.98	-	-	3.84	-	3.7	-	٧
PCP _{OUT} , PCn OUT Low-Level Output Voltage CMOS Loads	V _{OL}	V _{IL} or V _{IH}	-	4.5	-	-	0.1	-	0.1	-	0.1	V
PCP _{OUT} , PCn OUT Low-Level Output Voltage TTL Loads	V _{OL}	V _{IL} or V _{IH}	-	4.5	-	-	0.26	-	0.33	-	0.4	V
SIG _{IN} , COMP _{IN} Input Leakage Current	Ι _Ι	Any Voltage Between V _{CC} and GND	-	5.5	-	-	±30		±38		±45	μА
PC2 _{OUT} Three-State Off-State Current	l _{OZ}	V _{IL} or V _{IH}	-	5.5	-	-	±0.5	±5	-	-	±10	μА
SIG _{IN} , COMP _{IN} Input Resistance	R _I	V_{l} at Se Operatio ΔV_{l} = See Fig	n Point: 0.5V,	4.5	-	250	-	-	-	-	-	kΩ
DEMODULATOR SEC	CTION						_					_
Resistor Range	R _S	at R _S > Leakage Can Inf V _{DEM}	Current luence	4.5	5	-	300	-	-	-	-	kΩ
Offset Voltage VCO _{IN} to V _{DEM}	Voff	$V_{I} = V_{VO}$ $\frac{V_{CC}}{2}$ Values ta $R_{S} R_{i}$ See Fig	ken over ange	4.5	-	±20	-	-	-	-	-	mV
Dynamic Output Resistance at DEM _{OUT}	R _D	$\frac{V_{\text{DEM}}}{V_{\text{CC}}}$	TUC	4.5	-	25	-	-	-	-	-	Ω
Quiescent Device Current	Icc	V _{CC} or GND	-	5.5	-	-	8	-	80	-	160	μА
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 4)	V _{CC} -2.1 Excluding Pin 5	-	4.5 to 5.5	-	100	360	-	450	-	490	μА

- 2. The value for R1 and R2 in parallel should exceed 2.7k $\!\Omega.$
- 3. The maximum operating voltage can be as high as V_{CC} -0.9V, however, this may result in an increased offset voltage.
- 4. For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
INH	1

NOTE: Unit load is ΔI_{CC} limit specific in DC Electrical Specifications Table, e.g., 360 μ A max. at 25 o C.

Switching Specifications $C_L = 50pF$, Input t_r , $t_f = 6ns$

		TEST			25°C		-40°(85	С ТО °С		C TO 5°C	
PARAMETER	SYMBOL	CONDITIONS	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES					•	•				•	
PHASE COMPARATOR SECTI	ON										
Propagation Delay	t _{PLH} , t _{PHL}										
SIG_{IN} , $COMP_{IN}$ to PCI_{OUT}			2	-	-	200	-	250	-	300	ns
			4.5	-	-	40	-	50	-	60	ns
			6	-	-	34	-	43	-	51	ns
SIG_{IN} , $COMP_{IN}$ to PCP_{OUT}			2	-	-	300	-	375	-	450	ns
			4.5	-	-	60	-	75	-	90	ns
			6	-	-	51	-	64	-	77	ns
SIG _{IN} , COMP _{IN} to PC3 _{OUT}			2	-	-	245	-	305	-	307	ns
			4.5	-	-	49	-	61	-	74	ns
			6	-	-	42	-	52	-	63	ns
Output Transition Time	t _{THL} , t _{TLH}		2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Output Enable Time, SIG _{IN} ,	t _{PZH} , t _{PZL}		2	-	-	265	-	330	-	400	ns
COMP _{IN} to PC2 _{OUT}			4.5	ı	-	53	ı	66	1	80	ns
			6	ı	-	45	ı	56	1	68	ns
Output Disable Time, SIG _{IN} ,	t _{PHZ} , t _{PLZ}		2	-	-	315	-	395	-	475	ns
COMP _{IN} to PC2 _{OUT}			4.5	-	-	63	-	79	-	95	ns
			6	-	-	54	-	67	-	81	ns
AC Coupled Input Sensitivity		V _{I(P-P)}	3	-	11	-	-	-	-	-	mV
$(P-P)$ at SIG_{IN} or $COMP_{IN}$			4.5	-	15	-	-	-	-	-	mV
			6	-	33	-	-	-	-	-	mV
VCO SECTION											
Frequency Stability with	Δf	$R_1 = 100k\Omega$,	3	-	0.11	-	-	-	-	-	%/ºC
Temperature Change	$\overline{\Delta}\overline{T}$	R ₂ = ∞	4.5	-	0.11	-	-	-	-	-	%/ºC
			6	-	0.11	-	-	-	-	-	%/ºC
Maximum Frequency	f _{MAX}	C ₁ = 50pF	3	-	24	-	-	-	-	-	MHz
		$R_1 = 3.5k\Omega$ $R_2 = \infty$	4.5	-	24	-	-	-	-	-	MHz
		2	6	-	24	-	-	-	-	-	MHz
		C ₁ = 0pF	3	-	38	-	-	-	-	-	MHz
		$R_1 = 9.1k\Omega$ $R_2 = \infty$	4.5	-	38	-	-	-	-	-	MHz
		· · · Z	6	-	38	-	-	-	-	-	MHz

Switching Specifications $C_L = 50 pF$, Input t_r , $t_f = 6 ns$ (Continued)

		TEST			25°C		-40°(85			C TO 5°C	
PARAMETER	SYMBOL	CONDITIONS	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Center Frequency		$C_1 = 40pF$	3	7	10	-	-	-	-	-	MHz
		$R_1 = 3k\Omega$ $R_2 = \infty$	4.5	12	17	-	-	-	-	-	MHz
		VCO _{IN} = VCC/2	6	14	21	-	-	-	-	-	MHz
Frequency Linearity	Δf_{VCO}	$R_1 = 100k\Omega$	3	-	0.4	-	-	-	-	-	%
		$R_2 = \infty$ $C_1 = 100pF$	4.5	-	0.4	-	-	-	-	-	%
			6	-	0.4	-	-	-	-	-	%
Offset Frequency		$R_2 = 220k\Omega$	3	-	400	-	-	-	-	-	kHz
		C ₁ = 1nF	4.5	-	400	-	-	-	-	-	kHz
			6	-	400	-	-	-	-	-	kHz
DEMODULATOR SECTION	•									1	
V _{OUT} V _S f _{IN}		$R_1 = 100k\Omega$	3	-	-	-	-	-	-	-	mV/kHz
		$R_2 = \infty$ $C_1 = 100pF$	4.5	-	330	-	-	-	-	-	mV/kH
		$R_S = 10k\Omega$ $R_3 = 100k\Omega$ $C_2 = 100pF$	6	ı	-	-	-	-	-	-	mV/kHz
HCT TYPES		-Z			<u> </u>						
PHASE COMPARATOR SECT	ION										
Propagation Delay	t _{PHL} , t _{PLH}				<u> </u>					1	
SIG _{IN} , COMP _{IN} to PCI _{OUT}	PHL, PLH	$C_L = 50pF$	4.5	-	-	45	-	56	-	68	ns
SIG _{IN} , COMP _{IN} to PCP _{OUT}	t _{PHL} , t _{PLH}	C _L = 50pF	4.5	-	-	68	-	85	-	102	ns
SIG _{IN} , COMP _{IN} to PC3 _{OUT}	t _{PHL} , t _{PLH}	C _L = 50pF	4.5	-	-	58	-	73	-	87	ns
Output Transition Time	t _{TLH} , t _{THL}	C _L = 50pF	4.5	-	-	15	-	19	-	22	ns
Output Enable Time, SIG _{IN} , COMP _{IN} to PC2 _{OUT}	t _{PZH} , t _{PZL}	C _L = 50pF	4.5	-	-	60	-	75	-	90	pF
Output Disable Time, SIG_{IN} , $COMP_{IN}$ to PCZ_{OUT}	t _{PHZ} , t _{PLZ}	C _L = 50pF	4.5	-	-	68	-	85	-	102	pF
AC Coupled Input Sensitivity (P-P) at SIGIN or COMPI		V _{I(P-P)}	4.5	-	15	-	-	-	-	-	mV
VCO SECTION											
Frequency Stability with Temperature Change	$\frac{\Delta f}{\overline{\Delta T}}$	$R_1 = 100k\Omega$, $R_2 = \infty$	4.5	-	0.11	-	-	-	-	-	%/ºC
Maximum Frequency	f _{MAX}	$C_1 = 50pF$ $R_1 = 3.5k\Omega$ $R_2 = \infty$	4.5	-	24	-	-	-	-	-	MHz
		$C_1 = 0pF$ $R_1 = 9.1k\Omega$ $R_2 = \infty$	4.5	-	38	-	-	-	-	-	MHz
Center Frequency		$C_1 = 40pF$ $R_1 = 3k\Omega$ $R_2 = \infty$ $VCO_{IN} =$ $VCC/2$	4.5	12	17	-	-	-	-	-	MHz
Frequency Linearity	Δf _{VCO}	$R_1 = 100k\Omega$ $R_2 = \infty$ $C_1 = 100pF$	4.5	-	0.4	-	-	-	-	-	%

Switching Specifications $C_L = 50pF$, Input t_r , $t_f = 6ns$ (Continued)

		TEST			25°C		-40°(85°		-55 ⁰ (125		
PARAMETER	SYMBOL	CONDITIONS	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Offset Frequency		$R_2 = 220k\Omega$ $C_1 = 1nF$	4.5	-	400	-	-	-	-	-	kHz
DEMODULATOR SECTION											
Vout Vs fin		$R_1 = 100k\Omega$ $R_2 = \infty$ $C_1 = 100pF$ $R_S = 10k\Omega$ $R_3 = 100k\Omega$ $C_2 = 100pF$	4.5	-	330	-	-	-	-	-	mV/kHz

Test Circuits and Waveforms

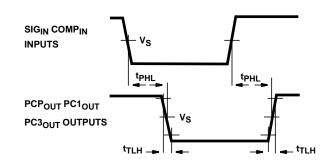


FIGURE 8. INPUT TO OUTPUT PROPAGATION DELAYS AND OUTPUT TRANSITION TIMES

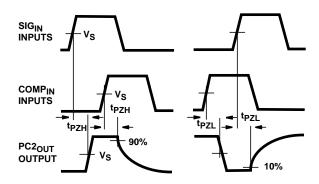


FIGURE 9. THREE STATE ENABLE AND DISABLE TIMES FOR $\mathsf{PC2}_\mathsf{OUT}$

Typical Performance Curves

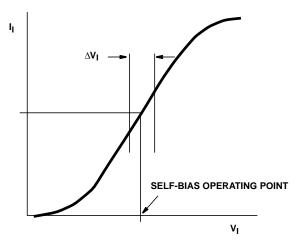


FIGURE 10. TYPICAL INPUT RESISTANCE CURVE AT SIG_{IN} , $COMP_{IN}$

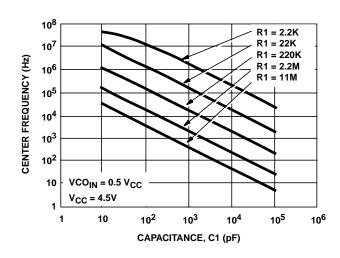


FIGURE 11. HC4046A TYPICAL CENTER FREQUENCY vs R1, C1 ($V_{CC} = 4.5V$)

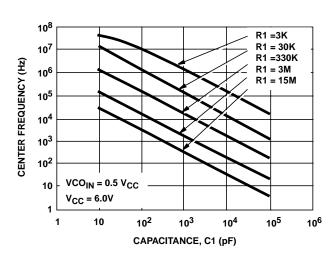


FIGURE 12. HC4046A TYPICAL CENTER FREQUENCY vs R1, C1 (V_{CC} = 6V)

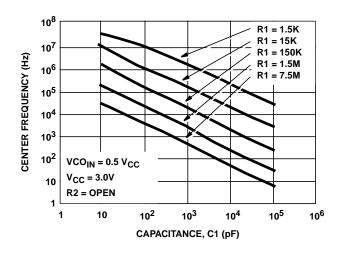


FIGURE 13. HC4046A TYPICAL CENTER FREQUENCY vs R1, C1 (V_{CC} = 3V, R2 = OPEN)

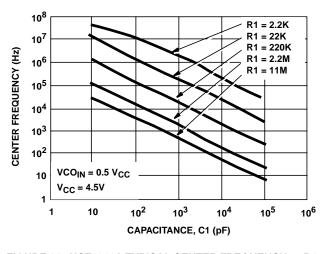


FIGURE 14. HCT4046A TYPICAL CENTER FREQUENCY vs R1, C1 (V_{CC} = 4.5V)

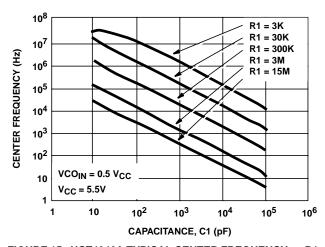


FIGURE 15. HCT4046A TYPICAL CENTER FREQUENCY vs R1, C1 ($V_{CC} = 5.5V$)

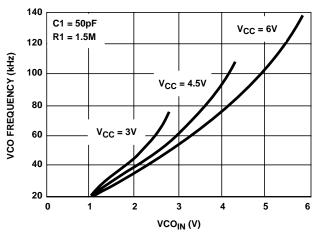


FIGURE 16. HC4046A TYPICAL VCO FREQUENCY vs VCO $_{\mbox{\scriptsize IN}}$ (R1 = 1.5M $_{\mbox{\scriptsize \Omega}}$, C1 = 50pF)

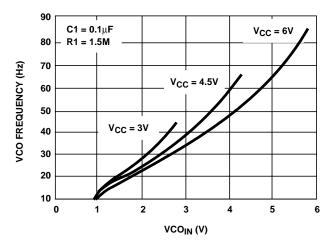


FIGURE 17. HC4046A TYPICAL VCO FREQUENCY vs VCO_IN (R1 = $1.5M\Omega$, C1 = $0.1\mu F$)

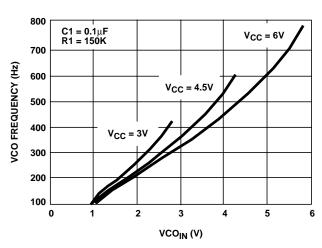


FIGURE 18. HC4046A TYPICAL VCO FREQUENCY vs VCO IN (R1 = 150k Ω , C1 = 0.1 μ F)

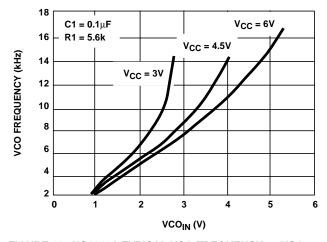


FIGURE 19. HC4046A TYPICAL VCO FREQUENCY vs VCO_{IN} $(R1 = 5.6k\Omega, C1 = 0.1\mu F)$

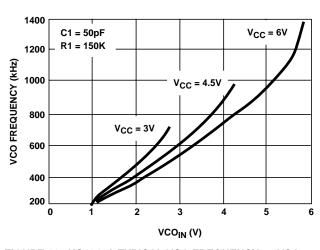


FIGURE 20. HC4046A TYPICAL VCO FREQUENCY vs VCO_{IN} (R1 = 150k Ω , C1 = 50pF)

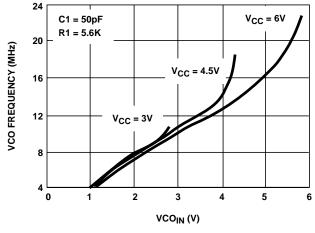


FIGURE 21. HC4046A TYPICAL VCO FREQUENCY vs VCO $_{IN}$ (R1 = 5.6k Ω , C1 = 50pF)

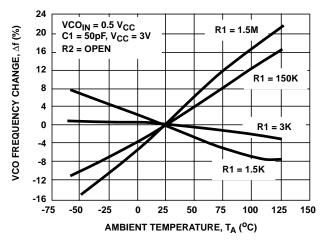


FIGURE 22. HC4046A TYPICAL CHANGE IN VCO FREQUENCY vs AMBIENT TEMPERATURE AS A FUNCTION OF R1 (V_{CC} = 3V)

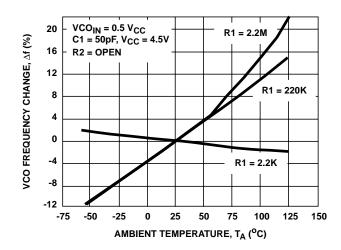


FIGURE 23. HC4046A TYPICAL CHANGE IN VCO FREQUENCY VS AMBIENT TEMPERATURE AS A FUNCTION OF R1 (V_{CC} = 4.5V)

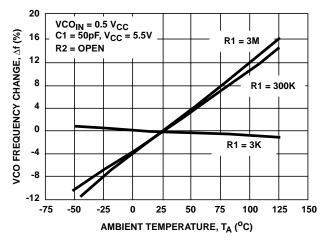


FIGURE 25. HCT4046A TYPICAL CHANGE IN VCO FREQUENCY vs AMBIENT TEMPERATURE AS A FUNCTION OF R1

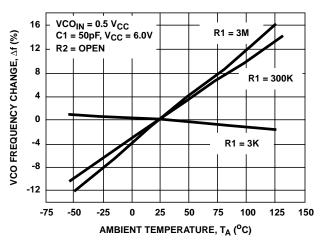


FIGURE 24. HC4046A TYPICAL CHANGE IN VCO FREQUENCY VS AMBIENT TEMPERATURE AS A FUNCTION OF R1 (V_{CC} = 6V)

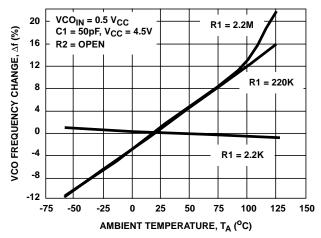


FIGURE 26. HC4046A TYPICAL CHANGE IN VCO FREQUENCY vs AMBIENT TEMPERATURE AS A FUNCTION OF R1 (V_{CC} = 4.5V)

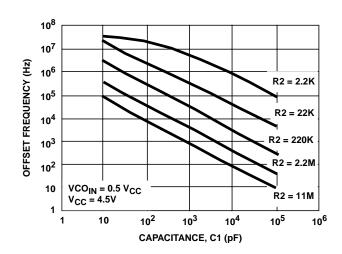


FIGURE 27. HC4046A OFFSET FREQUENCY vs R2, C1 ($V_{CC} = 4.5V$)

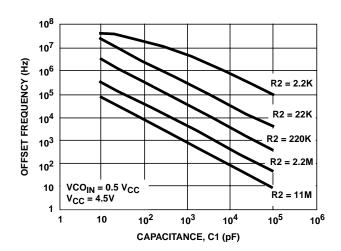


FIGURE 29. HCT4046A OFFSET FREQUENCY vs R2, C1 $(V_{CC} = 4.5V)$

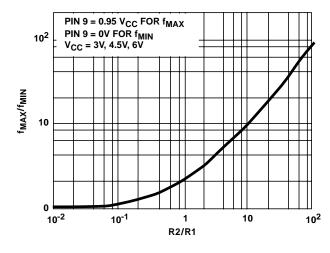


FIGURE 31. HC4046A f_{MIN}/f_{MAX} vs R2/R1 ($V_{CC} = 3V, 4.5V, 6V$)

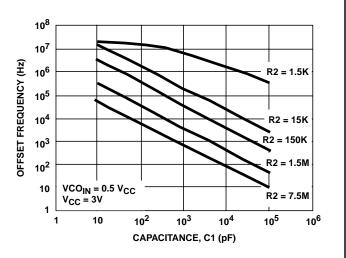


FIGURE 28. HC4046A OFFSET FREQUENCY vs R2, C1 $(V_{CC} = 3V)$

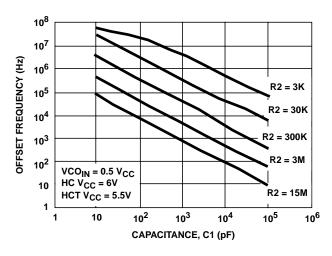


FIGURE 30. HC4046A AND HCT4046A OFFSET FREQUENCY vs R2, C1 (V_{CC} = 6V, V_{CC} = 5.5V)

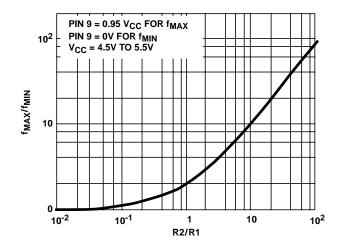


FIGURE 32. HCT4046A f_{MAX}/f_{MIN} vs R2/R1 ($V_{CC} = 4.5V$ TO 5.5V)

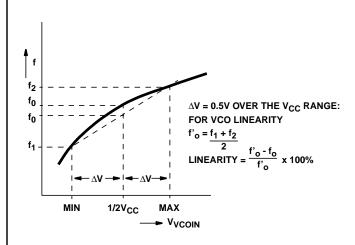


FIGURE 33. DEFINITION OF VCO FREQUENCY LINEARITY

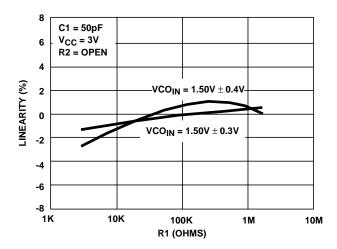


FIGURE 35. HC4046A VCO LINEARITY vs R1 (V_{CC} = 3V)

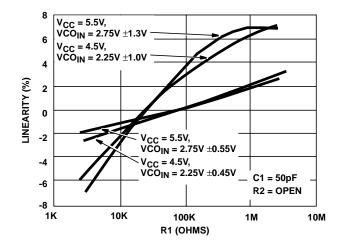


FIGURE 37. HCT4046A VCO LINEARITY vs R1 (V_{CC} = 4.5V, V_{CC} = 5.5V)

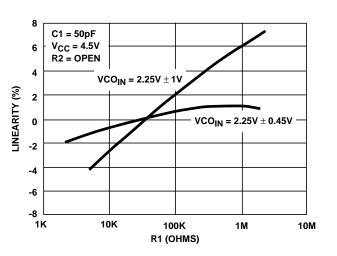


FIGURE 34. HC4046A VCO LINEARITY vs R1 (V_{CC} = 4.5V)

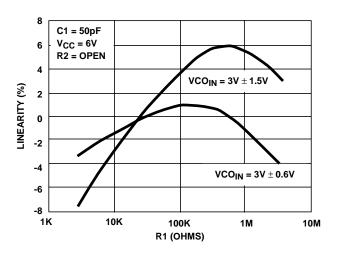


FIGURE 36. HC4046A VCO LINEARITY vs R1 (V_{CC} = 6V)

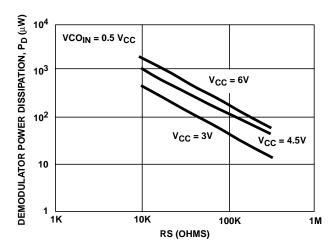
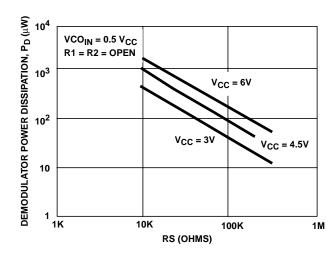


FIGURE 38. HC4046A DEMODULATOR POWER DISSIPATION vs RS (TYP) ($V_{CC} = 3V, 4.5V, 6V$)



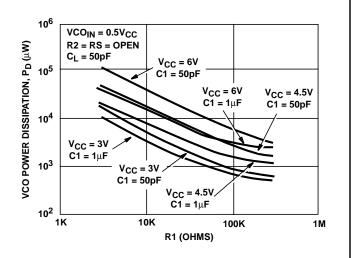
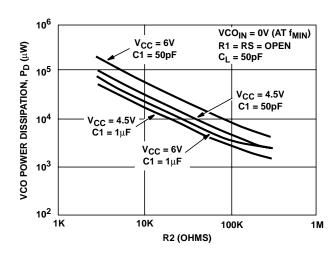


FIGURE 39. HCT4046A DEMODULATOR POWER DISSIPATION vs RS (TYP) (V_{CC} = 3V, 4.5V, 6V)





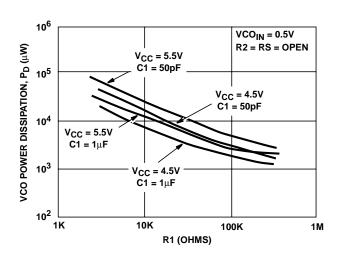


FIGURE 41. HCT4046A VCO POWER DISSIPATION vs R2 (C1 = 50pF, 1μ F)

FIGURE 42. HCT4046A VCO POWER DISSIPATION vs R1 (C1 = 50pF, 1μ F)

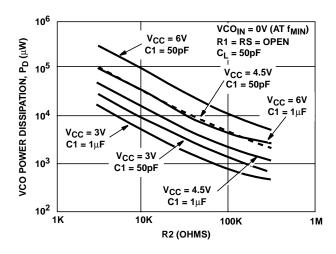


FIGURE 43. HC4046A VCO POWER DISSIPATION vs R2 (C1 = 50pF, 1μ F)

HC/HCT4046A CPD

CHIP SECTION	нс	нст	UNIT
Comparator 1	48	50	pF
Comparators 2 and 3	39	48	pF
vco	61	53	pF

Application Information

This information is a guide for the approximation of values of external components to be used with the 'HC4046A and 'HCT4046A in a phase-lock-loop system.

References should be made to Figures 11 through 15 and Figures 27 through 32 as indicated in the table.

Values of the selected components should be within the following ranges:

R1	Between $3k\Omega$ and $300k\Omega$
R2	Between $3\text{k}\Omega$ and $300\text{k}\Omega$
R1 + R2	Parallel Value > $2.7k\Omega$
C1	Greater Than 40pF

SUBJECT	PHASE COMPARATOR	DESIGN CONSIDERATIONS
VCO Frequency Without Extra Offset	PC1, PC2 or PC3	VCO Frequency Characteristic With R2 = ∞ and R1 within the range 3kΩ < R1 < 300kΩ, the characteristics of the VCO operation will be as shown in Figures 11 - 15. (Due to R1, C1 time constant a small offset remains when R2 = ∞ .)
		f _{MAX}
		fvco
		f _o • 2f _L
		f _{MIN} MIN 1/2 V. a V. a cur. MAX
		MIN 1/2 V _{CC} V _{VCOIN} MAX FIGURE 44. FREQUENCY CHARACTERISTIC OF VCO OPERATING WITHOUT OFFSET: f _o = CENTER FREQUENCY: 2f _L = FREQUENCY LOCK RANGE
PC	PC1	Selection of R1 and C1 Given f ₀ , determine the values of R1 and C1 using Figures 11 - 15
	PC2 or PC3	Given f_{MAX} calculate f_0 as $f_{MAX}/2$ and determine the values of R1 and C1 using Figures 11 - 15. To obtain $2f_L$: $2f_L \approx 1.2 \ (V_{CC} - 1.8V)/(R1C1)$ where valid range of VCO_{IN} is $1.1V < VCO_{IN} < V_{CC} - 0.9V$
VCO Frequency with Extra Offset	PC1, PC2 or PC3	VCO Frequency Characteristic With R1 and R2 within the ranges $3k\Omega < R1 < 300k\Omega$, $3k\Omega$, $< R2 < 300k\Omega$, the characteristics of the VCO operation will be as shown in Figures 27 - 32.
		f _{MAX} f _{vco}
		f _o = 2f _L
		f _{MIN} —
		MIN 1/2 V _{CC} V _{VCOIN} MAX
		FIGURE 45. FREQUENCY CHARACTERISTIC OF VCO OPERATING WITH OFFSET: f _o = CENTER FREQUENCY: 2f _L = FREQUENCY LOCK RANGE
	PC1, PC2 or PC3	Selection of R1, R2 and C1 Given f_0 and f_L , offset frequency, f_{MIN} , may be calculated from $f_{MIN} \approx f_0$ - 1.6 f_L . Obtain the values of C1 and R2 by using Figures 27 - 30. Calculate the values of R1 from Figures 31 - 32.

SUBJECT	PHASE COMPARATOR	DESIGN CONSIDERATIONS					
PLL Conditions with	PC1	VCO adjusts to f _o with $\phi_{DEMOUT} = 90^{o}$ and $V_{VCOIN} = 1/2 V_{CC}$ (see Figure 2)					
No Signal at the	PC2	VCO adjusts to f _{MIN} with ϕ_{DEMOUT} = -360° and V_{VCOIN} = 0V (see Figure 4)					
SIG _{IN} Input	PC3	VCO adjusts to f_{MAX} with $\phi_{DEMOUT} = 360^{\circ}$ and $V_{VCOIN} = V_{CC}$ (see Figure 6)					
PLL Frequency Capture Range	PC1, PC2 or PC3	Loop Filter Component Selection					
		INPUT C2 OUTPUT (A) $\tau = R3 \times C2$ (B) AMPLITUDE CHARACTERISTIC (C) POLE-ZERO DIAGRAM A small capture range $(2f_c)$ is obtained if $\tau > 2f_c \approx 1/\pi \ (2\pi f_1/\tau.)^{1/2}$					
PLL Locks on	PC1 or PC3	FIGURE 46. SIMPLE LOOP FILTER FOR PLL WITHOUT OFFSET $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$					
PLL Locks on Harmonics at Center							
Frequency	PC2	No					
Noise Rejection at	PC1	High					
Signal Input	PC2 or PC3	Low					
AC Ripple Content	PC1	$f_r = 2f_i$, large ripple content at $\phi_{DEMOUT} = 90^{\circ}$					
when PLL is Locked	PC2	$f_r = f_i$, small ripple content at $\phi_{DEMOUT} = 0^0$					
	PC3	$f_r = fSIG_{IN}$, large ripple content at $\phi_{DEMOUT} = 180^{\circ}$					



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-8875701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8960901EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HC4046AF	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HC4046AF3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HCT4046AF3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD74HC4046AE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC4046AEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC4046AM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046AM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046AM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046AM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046AME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046AMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046AMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046AMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046AMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046APWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC4046APWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4046AE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT4046AEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type



PACKAGE OPTION ADDENDUM

9-Oct-2007

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
CD74HCT4046AM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4046AM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4046AM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4046AM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4046AME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4046AMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4046AMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4046AMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT4046AMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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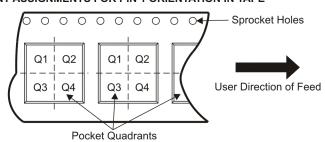
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC4046AM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4046ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC4046APWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
CD74HCT4046AM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4046AM96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HC4046ANSR	SO	NS	16	2000	346.0	346.0	33.0
CD74HC4046APWR	TSSOP	PW	16	2000	346.0	346.0	29.0
CD74HCT4046AM96	SOIC	D	16	2500	333.2	345.9	28.6

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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